



Full Material Declaration for attached parts list

Report generated: 02 December 2025, 10:18 GMT



Diotec Semiconductor AG
DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 02 December 2025, 10:17 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.32%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.5%
			ALUMINUM, ELEMENTAL	7429-90-5	1%
			Elemental silicon	7440-21-3	98.5%
Encapsulation	EP (Epoxy resin)	52.04%	Carbon black	1333-86-4	0.1%
			Phenol, polymer with formaldehyde	9003-35-4	6%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	9%
			Quartz (SiO2) Exempt from other regulatory requirements	14808-60-7	84.9%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	1.43%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.7%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	45.51%	SILVER, ELEMENTAL	7440-22-4	0.41%
			Elemental zinc	7440-66-6	0.52%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	0.7%
			Tin elemental	7440-31-5	1%
			COPPER, ELEMENTAL	7440-50-8	97.37%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-323 (AO) PbF & HF sin.	Diode / Transistor SMD	0.006305	g
